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Customer No.: 31561
Docket No.: 13304-US-PA.
Application No.: 10/710,599

AMENDMENTS

IN THE CLAIMS:

Claim 1. (currently amended) A method of manufacturing a color filter array, comprising the steps of:

(a) forming a patterned first photoresist layer over a substrate, wherein the first photoresist layer has a plurality of openings with each opening exposing a portion of the substrate;

(b) forming a filter material layer over the exposed substrate within the openings and the first photoresist layer;

(c) forming a second photoresist layer over the filter material layer within the openings and exposing the filter material layer over the first photoresist layer;

(d) removing the filter material layer over the first photoresist layer;

~~[[(d)]]~~ (e) removing the first photoresist layer and the second photoresist layer to form a plurality of first color filter films; and

~~[[(e)]]~~ (f) repeating the steps from (a) to ~~[[(c)]]~~ (d) at least once and removing the first photoresist layer and the second photoresist layer to form a plurality of second color filter films on the substrate in areas except the first color filter films.

Claims 2-3.(canceled)

Claim 4. (currently amended) The method of claim 1, wherein the filter material layer has a thickness smaller than the first photoresist layer such that the filter material layer within the openings is separated from the filter material layer over the first photoresist layer.

Claim 5. (original) The method of claim 1, wherein the filter material layer has a

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thickness equal to the first photoresist layer.

Claim 6. (currently amended) A method of manufacturing a thin film on a substrate, comprising ~~the steps of~~:

(a) forming a patterned first photoresist layer over the substrate, wherein the first photoresist layer has a plurality of openings with each opening exposing a portion of the substrate;

(b) forming a filter material layer over the exposed substrate within the openings and the first photoresist layer;

(c) forming a second photoresist layer over the filter material layer within the openings and exposing the filter material layer over the first photoresist layer;

(d) removing the filter material layer over the first photoresist layer;

~~[[d]]~~(e) removing the first photoresist layer and the second photoresist layer to form a plurality of first color filter~~[[thin]]~~ films.

Claims 7-8 (canceled)

Claim 9. (currently amended) The method of claim 6, wherein the material layer has a thickness smaller than the first photoresist layer such that the filter material layer within the openings is separated from the filter material layer over the first photoresist layer.

Claim 10. (original) The method of claim 6, wherein the material layer has a thickness equal to the first photoresist layer.